Computer Memory Test Labs
Intel® Approved Final Test Report

Manufacturer Name: ATP Electronics
Manufacturer Part #: X4B32QB4BNRCSE-B
Module Size: 32GB
Module Config: 4096M x 72
DRAM Manufacturer: Samsung
DRAM Part #: K4A8G045WB-BCRC rev B
PCB Part #: S4B288B04Q2 Rev B
PCB Layer Count: 12 Layer
Module Info: Registered 1.2V
Assembly: JEDEC Standard
Register Part: iDDR4RCD-GS02
Environment Code: RoHS-Halogen Free
Low Profile: 30mm LP
Cas Latency: 17
Bank: 4
Minimum System: S2600WT
Maximum System: S2600WT

Min Configuration memory speed ran @ 2400MHz
Mid configuration memory speed ran @ 2133MHz, memory count 512GB
Max configuration memory speed ran @ 1600MHz